For assistance or to order; call (800) 531-5782

78SR100 Series

1.5 AMP POSITIVE STEP-DOWN INTEGRATED SWITCHING REGULATOR

Revised 6/30/98



| Characteristics | | | 78SR10 | | | |
|---|---------------------|--|-----------|-----------|----------|-----------------------------|
| (T _a = 25°C unless noted) | Symbols | Conditions | Min | Тур | Max | Units |
| Output Current | Io | Over V _{in} range | 0.1* | - | 1.5 | Α |
| Short Circuit Current | I _{sc} | V _{in} = V _{in} min | | 3.5 | _ | Apk |
| Input Voltage Range | V_{in} | $0.1 \le I_o \le 1.5A$ $V_o = 5V$ $V_o = 12V$ | 7 14.5 | Ξ | 30 30 | V V |
| Output Voltage Tolerance | ΔV_{o} | Over V_{in} range, $I_o=1.5A$ $T_a = 0^{\circ}C$ to +60°C | — | ±1.0 | ±2.0 | %V ₀ |
| Line Regulation | Reg _{line} | Over V _{in} range | | ±0.2 | ±0.4 | %Vo |
| Load Regulation | Reg _{load} | $0.1 \le I_o \le 1.5 A$ | _ | ±0.1 | ±0.2 | %Vo |
| V _o Ripple/Noise | V _n | V_{in} = 9V, I_o = 1.5A V_o = 5V V_{in} = 16V, I_o = 1.5A V_o = 12V | — | 50 80 | — | ${ m mV_{pp}} { m mV_{pp}}$ |
| Transient Response | t _{tr} | 50% load change V _o over/undershoot | _ | 100 30 | _ | μSec %Vo |
| Efficiency | η | $V_{in} = 10V, I_o = 1A$ $V_o = 5V$ $V_{in} = 17V, I_o = 1A$ $V_o = 12V$ | _ | 85 90 | _ | % % |
| Switching Frequency | f_{o} | Over V _{in} range, I _o =1.5A | 600 | 650 | 700 | kHz |
| Absolute Maximum Operating Temperature Range | Ta | _ | -40 | - | +85 | °C |
| Recommended Operating Temperature Range | T _a | Free Air Convection, (40-60LFM) At V _{in} = 24V, I _o =1.0A | -40 | _ | +80** | °C |
| Thermal Resistance | θ_{ia} | Free Air Convection, (40-60LFM) | | 45 | | °C/W |
| Storage Temperature | T _s | | -40 | _ | +125 | °C |
| Mechanical Shock | _ | Per Mil-STD-883D, Method 2002.3 | | 500 | | G's |
| Mechanical Vibration | _ | Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board | _ | 5 | _ | G's |
| Weight | | | | 6.5 | | grams |

*ISR will operate down to no load with reduced specifications.

**See Thermal Derating chart.

e s

78SR100

CHARACTERISTIC

DATA



Note 1: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the ISR. Note 2: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM. (See Thermal Application Notes.)



2-Feb-2014

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package | Pins Package | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|---------|--------------|---------|--------------|----------|------------------|---------------|--------------|----------------|---------|
| | (1) | | Drawing | Qty | (2) | (6) | (3) | | (4/5) | |
| 78SR105SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR106SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR108SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR109SC | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR109SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR110SC | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR110SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR110VC | OBSOLET | E SIP MODULE | EFD | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR112SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR114SC | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR114SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR114WC | OBSOLET | E SIP MODULE | EFW | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR115SC | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR115SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR153SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR153TC | OBSOLET | E SIP MODULE | EFT | 3 | TBD | Call TI | Call TI | -40 to 85 | | |
| 78SR174SCT | OBSOLET | E SIP MODULE | EFC | 3 | TBD | Call TI | Call TI | -40 to 85 | | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



2-Feb-2014

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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